

In the Claims:

Claims 1-51 (canceled).

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Claim 52 (currently amended). An electronic device,
comprising:

a substrate having a surface; and

an electronic circuit having interconnects formed on said
surface of said substrate;

said electronic circuit including at least one microscopically
small contact area;

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said contact area including a microscopically small contact
element disposed thereon having a base and a part that is
integrally formed with said base and connected to said contact
area in one piece, said contact area extending from said
contact area in three dimensions in a direction deviating from
a direction parallel to said electronic circuit on said
substrate, said part extending from said contact area being
angularly disposed relative to said substrate in an unstressed
condition.

Claim 53 (original). The electronic device according to claim 52, in combination with an intermediate carrier having a contact connection area and flat conductors, wherein:

said contact area of the electronic device is configured opposite the contact connection area of the intermediate carrier.

Claim 54 (original). The electronic device according to claim 52, wherein:

said substrate is selected from the group consisting of a semiconductor chip and a semiconductor wafer; and

said electronic circuit includes at least one integrated circuit near said surface of said substrate.

Claim 55 (original). The electronic device according to claim 52, wherein

said interconnects have ends; and

said at least one contact area includes a plurality of contact areas, each one of said plurality of said contact areas configured on a respective one of said ends of said interconnects.

Claim 56 (original). The electronic device according to claim 52, wherein said contact element is elastically deformable.

Claim 57 (original). The electronic device according to claim 52, wherein said contact element is preformed at a solid angle that deviates from a direction orthogonal to said surface.

Claim 58 (original). The electronic device according to claim 52, wherein said contact element is pre-bent at a solid angle that deviates from a direction orthogonal to said surface.

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Claim 59 (currently amended). The electronic device according to claim 52, wherein said surface of said substrate has a largest bulging area and said contact element has a length that is at least 5% greater than said largest bulging area of said surface of said substrate.

Claim 60 (original). The electronic device according to claim 52, in combination with an intermediate carrier having a contact connection area and flat conductors, wherein:

said contact area of the electronic device is configured opposite the contact connection area of the intermediate carrier; and

said contact element has a length that is at least 5% greater than a largest distance between said contact area and the contact connection area of the intermediate carrier.

Claim 61 (original). The electronic device according to claim 52, wherein:

said substrate has a centrally located neutral point; and

said contact element has a length that is at least 5% greater than a largest length difference with regard to said centrally located neutral point of the substrate in an event of maximum thermal cycling.

Claim 62 (original). The electronic device according to claim 52, in combination with an intermediate carrier having a contact connection area and flat conductors, wherein:

said contact area of the electronic device is configured opposite the contact connection area of the intermediate carrier;

said substrate of the electronic device has a centrally located neutral point; and

said contact element has a length that is at least 5% greater than a largest length difference between said substrate and the intermediate carrier relative to said centrally located neutral point of said substrate in an event of maximum thermal cycling.

Claim 63 (original). The electronic device according to claim 52, wherein said contact area and said contact element are produced from an identical metal alloy.

Claim 64 (original). The electronic device according to claim 52, wherein said contact area is produced from an aluminum alloy and said contact element is produced from a gold alloy.

Claim 65 (original) The electronic device according to claim 52, wherein said contact area is produced from an aluminum alloy and said contact element is produced from a copper alloy.

Claim 66 (original). The electronic device according to claim 52, wherein said contact element is designed as a contact pin.

Claim 67 (original). The electronic device according to claim 52, in combination with an intermediate carrier having a contact connection area and flat conductors, wherein:

said contact area of the electronic device is configured opposite the contact connection area of the intermediate carrier;

 said substrate of the electronic device has a centrally located neutral point;

 said contact element has a length that is at least 5% greater than a largest length difference between said substrate and the intermediate carrier relative to said centrally located neutral point of said substrate in an event of maximum thermal cycling;

 said contact area has a shortest linear dimension; and

 said contact element is designed as a contact pin that has a diameter which is not greater than half of said shortest linear dimension of said contact area.

Claim 68 (original). The electronic device according to claim 52, in combination with an intermediate carrier having a contact connection area and flat conductors, wherein:

 said contact area of the electronic device is configured opposite the contact connection area of the intermediate carrier;

said substrate of the electronic device has a centrally located neutral point;

said contact element has a length that is at least 5% greater than a largest length difference between said substrate and the intermediate carrier relative to said centrally located neutral point of said substrate in an event of maximum thermal cycling;

said contact element is designed as a contact pin having an end with a contact head; and

said end of said contact pin is remote from said contact area.

Claim 69 (original). The electronic device according to claim 52, comprising:

a coating selected from the group consisting of a nickel coating and a gold coating;

said contact element is designed as a contact pin having an end with a contact head that is coated with said coating; and

said end of said contact pin is remote from said contact area.

Claim 70 (original). The electronic device according to claim 52, comprising:

a coating made of a solderable metal alloy;

said contact element is designed as a contact pin having an end with a contact head that is coated with said coating; and

said end of said contact pin is remote from said contact area.

Claim 71 (original). The electronic device according to claim 52, wherein

said contact element is designed as a contact pin having an end with a contact head made from solder; and

said end of said contact pin is remote from said contact area.

Claims 72-77 (canceled).

Claims 78-104 (withdrawn).

Claim 105 (new). An electronic device, comprising:

a substrate having a surface; and

an electronic circuit having interconnects formed on said surface of said substrate;

said electronic circuit including at least one microscopically small contact area;

said contact area having a shortest linear dimension and including a microscopically small contact element disposed thereon having a base and a part integrally formed with said base and extending from said contact area in three dimensions in a direction deviating from a direction parallel to said electronic circuit on said substrate, said part extending from said contact area being angularly disposed relative to said substrate in an unstressed condition, and said contact element being configured as a contact pin having a diameter not being greater than half of said shortest linear dimension of said contact area.

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Claim 106 (new). The electronic device according to claim 52, wherein said part extending from said base has a substantially pin-shaped configuration.

Claim 107 (new). The electronic device according to claim 52, wherein said part extending from said base has a free end opposite said base and is configured for detachably receiving a test head.

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